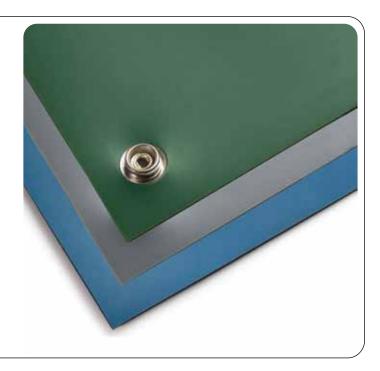


ESD Bench Matting - Smooth Finish

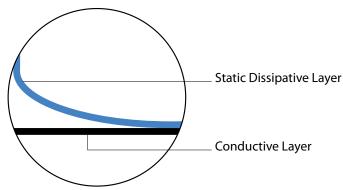
Features:

Anti-static matting should be laid out in the workshops or advanced laboratories for microelectronic industries such as electronic semi-conduct devices, electronic computers, electronic communication equipment and integrated circuits etc.

- Great value ESD Bench Matting
- Made from anti-static (conductive) and static-dissipative materials with synthetic rubber
- 2mm thick double-layer structure
- Surface layer is a 0.5mm thick static-dissipative layer
- Bottom layer is a 1.5mm conductive layer
- · Available in blue, grey or green
- · Asian origin



Construction:



Colours / Finish:

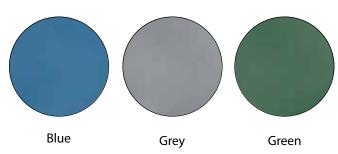
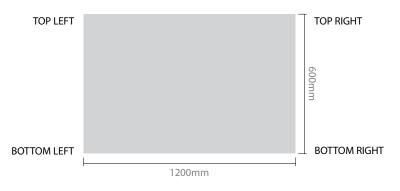


Fig 1: Stud Positioning



Requesting Cut Mats with Studs:

If ordering pre cut mats and you require studs to be added, please ensure that the position of the stud is specified as per Fig 1.



ESD Bench Matting - Smooth Finish

GROUNDING:

Sufficient ground cords should be used to reliably meet EN 61340-5-1 Table 3 less than $1 \times 10^{\circ}$ ohms for working surfaces. Industry recommendation is that continuous runs of ESD matting should be grounded at 10ft intervals to allow proper charge decay rates. Each individual ESD mat should be grounded with ground snaps located no further than five feet from either end.

CLEANING:

Please note that contact between the matting surface and any acid or alkali solvent is strictly prohibited (such as Benzene, Alcohol etc), this will result in the antistatic performance wearing away. If cleaning is required, the matting may be wiped with a cloth coated in a neutral solution (such as water).

GUIDANCE ON USE:

Matting materials have a tendency to shrink slightly when first unrolled. In applications where length is critical, allow the material to relax for at least 4 hours before cutting to size. Matting should always be trimmed with a sharp knife or razor blade.

CUTTING TOLERANCES:

Width + 6mm

Length ± 6mm every linear foot of running material

RoHS COMPLIANCE:

None of the following materials are intentionally added in manufacturing this product: lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE) as outlined in the Directive 2002/95/FC Article 4.1.



Test Results:

	Test Method:	Unit:	Value:
Surface Resistance / R _{TG}	SJ/T10694-2004	Ω	$1x10^6 \le R \le 1x10^9$
Bottom Resistance / R _{TT}	SJ/T10694-2004	Ω	$1x10^3 \le R \le 1x10^6$
Volume Resistance	GB/T14437-97	Ω	$1x10^{5} \le R \le 1x10^{8}$
Thickness	YY-1001	mm	Permissable Tolerance +0.1
Temperature Resistance	YY-1001	°C	180 (Instantaneous Temp)
Temperature	N/A	∘⊂	20-26
Relative Humidity	N/A	%	40-65

 R_{TG} is the resistance from one point on the mat's surface to the mat's ground point, and is the fundamental electrical test for a mat. A proper R_{TG} insures that a mat can conduct charge from a point on the surface to the mat ground point. The guideline in ESD STM-4.1 for R_{TG} is 1×10^6 to 1×10^9 ohms. ANSI/ESD S-20.20 has an upper limit of <1 $\times10^9$ ohms.

 R_{TT} is the resistance from one point on the mat's surface to another point. A proper R_{TT} insures the consistency of the mat's resistance properties. The ESD STM-4.1 guideline for R_{TT} is >1x10⁶ ohms.